

## SYNCHRONOUS BOOST CONVERTER WITH 2A SWITCH

### FEATURES

- **Synchronous (96% Efficient) Boost Converter With 500-mA Output Current From 1.8-V Input**
- **Available in a 16-Pin QFN 4 x 4 Package**
- **Device Quiescent Current: 20- $\mu$ A (Typ)**
- **Input Voltage Range: 1.8-V to 5.5-V**
- **Adjustable Output Voltage Up to 5.5-V Fixed Output Voltage Options**
- **Power Save Mode for Improved Efficiency at Low Output Power**
- **Low Battery Comparator**
- **Low EMI-Converter (Integrated Antiringing Switch)**
- **Load Disconnect During Shutdown**
- **Over-Temperature Protection**

### APPLICATIONS

- **All Single Cell Li or Dual Cell Battery, or USB Powered Operated Products as MP-3 Player, PDAs, and Other Portable Equipment**

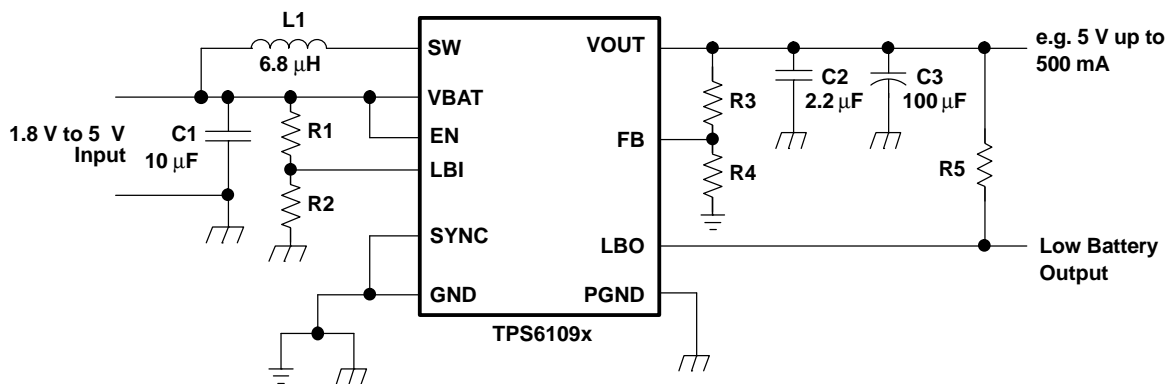
### DESCRIPTION

The TPS6109x devices provide a power supply solution for products powered by either a one-cell Li-Ion or Li-polymer, or a two-cell alkaline, NiCd or NiMH battery and required supply currents up to or higher than 1 A. The converter generates a stable output voltage that is either adjusted by an external resistor divider or fixed internally on the chip. It provides high efficient power conversion and is capable of delivering output currents up to 0.5 A at 5 V at a supply voltage down to 1.8 V. The implemented boost converter is based on a fixed frequency, pulse-width- modulation (PWM) controller using a synchronous rectifier to obtain maximum efficiency. Boost switch and rectifier switch are connected internally to provide the lowest leakage inductance and best EMI behavior possible. The maximum peak current in the boost switch is limited to a value of 2500 mA.

The converter can be disabled to minimize battery drain. During shutdown, the load is completely disconnected from the battery. A low-EMI mode is implemented to reduce ringing and, in effect, lower radiated electromagnetic energy when the converter enters the discontinuous conduction mode.

The output voltage can be programmed by an external resistor divider or is fixed internally on the chip.

The device is packaged in a 16-pin QFN 4 x 4 mm (16 RSA) package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

### AVAILABLE OUTPUT VOLTAGE OPTIONS<sup>(1)</sup>

T <sub>A</sub>	OUTPUT VOLTAGE DC/DC	PACKAGE	Part Number <sup>(2)</sup>
40°C to 85°C	Adjustable	16-Pin QFN 4x4mm	TPS61090RSA
	3.3 V	16-Pin QFN 4x4mm	TPS61091RSA
	5 V	16-Pin QFN 4x4mm	TPS61092RSA

- (1) Contact the factory to check availability of other fixed output voltage versions.  
(2) The RSA package is available taped and reeled. Add R suffix to device type (e.g., TPS61090RSAR) to order quantities of 3000 devices per reel.

### ABSOLUTE MAXIMUM RATINGS

over operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

	TPS6109x
Input voltage range on LBI	-0.3 V to 3.6 V
Input voltage range on SW, VOUT, LBO, VBAT, SYNC, EN, FB	-0.3 V to 7 V
Operating free air temperature range T <sub>A</sub>	-40°C to 85°C
Maximum junction temperature T <sub>J</sub>	150°C
Storage temperature range T <sub>stg</sub>	-65°C to 150°C

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

### RECOMMENDED OPERATING CONDITIONS

	MIN	NOM	MAX	UNIT
Supply voltage at VBAT, V <sub>I</sub>	1.8		5.5	V
Inductance, L	2.2	6.8		μH
Input, capacitance, C <sub>i</sub>		10		μF
Output capacitance, C <sub>o</sub>	22	100		μF
Operating free air temperature, T <sub>A</sub>	-40		85	°C
Operating virtual junction temperature, T <sub>J</sub>	-40		125	°C

### ELECTRICAL CHARACTERISTICS

over recommended free-air temperature range and over recommended input voltage range (typical values are at an ambient temperature range of 25°C) (unless otherwise noted)

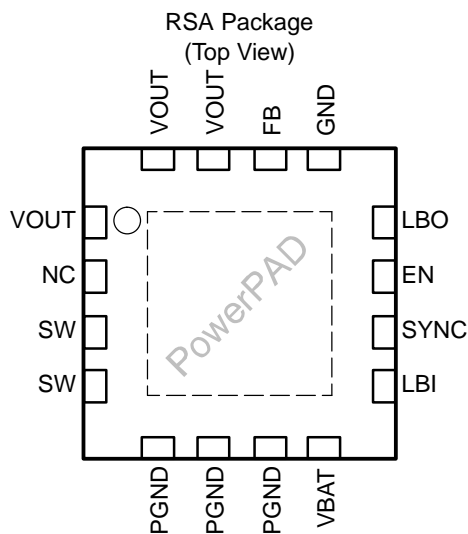
DC/DC STAGE						
PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
V <sub>I</sub>	Input voltage range		1.8		5.5	V
V <sub>O</sub>	TPS61090 output voltage range		1.8		5.5	V
V <sub>FB</sub>	TPS61090 feedback voltage		490	500	510	mV
f	Oscillator frequency		500	600	700	kHz
	Frequency range for synchronization		500		700	kHz
I <sub>SW</sub>	Switch current limit	VOUT= 5 V	2000	2200	2500	mA
	Start-up current limit			0.4 x I <sub>SW</sub>		mA
	Boost switch on resistance	VOUT= 5 V		55		mΩ
	Rectifying switch on resistance	VOUT= 5 V		55		mΩ
	Total accuracy		-3%		3%	
	Line regulation				0.6%	

## Electrical Characteristics (continued)

over recommended free-air temperature range and over recommended input voltage range (typical values are at an ambient temperature range of 25°C) (unless otherwise noted)

DC/DC STAGE						
PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
Load regulation					0.6%	
Quiescent current	into VBAT	$I_O = 0 \text{ mA}$ , $V_{EN} = V_{BAT} = 1.8 \text{ V}$ , $V_{OUT} = 5 \text{ V}$		10	25	$\mu\text{A}$
	into VOUT	$I_O = 0 \text{ mA}$ , $V_{EN} = V_{BAT} = 1.8 \text{ V}$ , $V_{OUT} = 5 \text{ V}$		10	20	$\mu\text{A}$
Shutdown current		$V_{EN} = 0 \text{ V}$ , $V_{BAT} = 2.4 \text{ V}$		0.1	1	$\mu\text{A}$
CONTROL STAGE						
PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
$V_{UVLO}$	Under voltage lockout threshold	$V_{LBI}$ voltage decreasing		1.5		V
$V_{IL}$	LBI voltage threshold	$V_{LBI}$ voltage decreasing	490	500	510	mV
	LBI input hysteresis			10		mV
	LBI input current	$EN = V_{BAT}$ or GND		0.01	0.1	$\mu\text{A}$
	LBO output low voltage	$V_O = 3.3 \text{ V}$ , $I_{OI} = 100 \mu\text{A}$		0.04	0.4	V
	LBO output low current			100		$\mu\text{A}$
	LBO output leakage current	$V_{LBO} = 7 \text{ V}$		0.01	0.1	$\mu\text{A}$
$V_{IL}$	EN, SYNC input low voltage			$0.2 \times V_{BAT}$		V
$V_{IH}$	EN, SYNC input high voltage		$0.8 \times V_{BAT}$			V
	EN, SYNC input current	Clamped on GND or VBAT		0.01	0.1	$\mu\text{A}$
	Overtemperature protection			140		°C
	Overtemperature hysteresis			20		°C

## PIN ASSIGNMENTS



## Terminal Functions

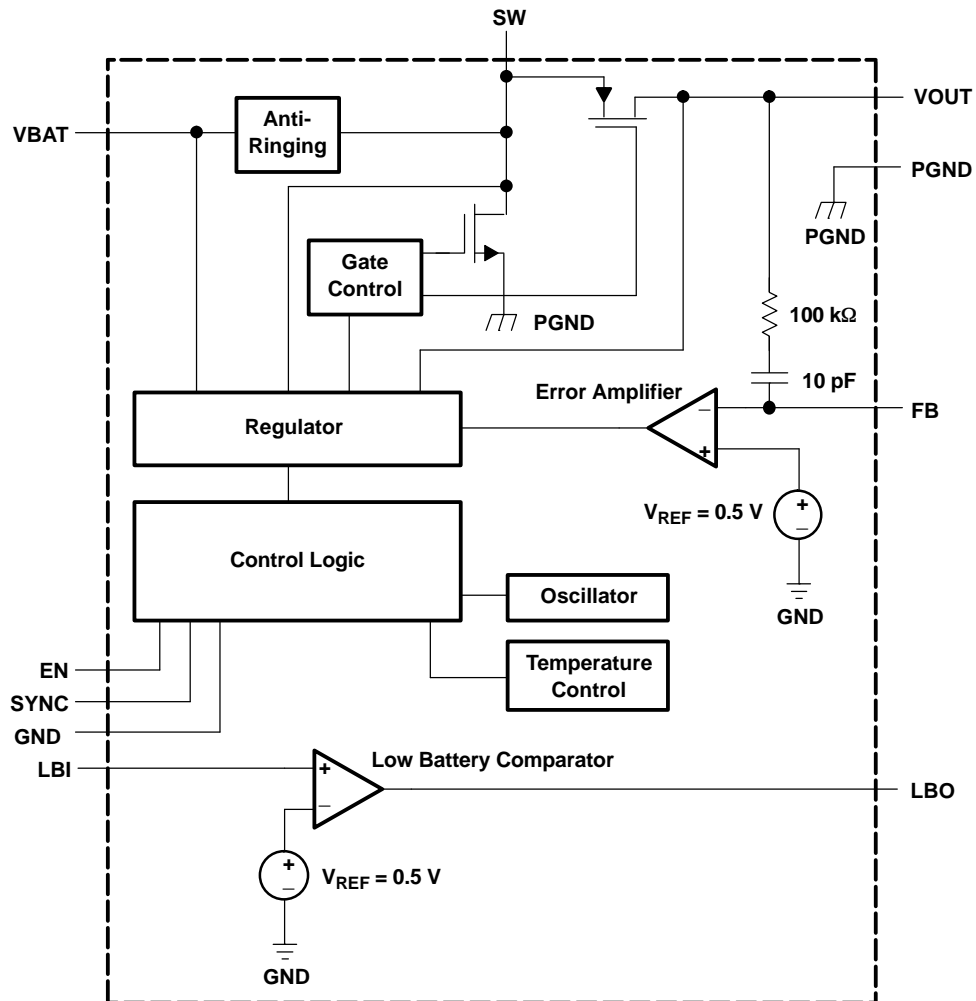
TERMINAL		I/O	DESCRIPTION
NAME	NO.		
EN	11	I	Enable input. (1/VBAT enabled, 0/GND disabled)
FB	14	I	Voltage feedback of adjustable versions

Pin Assignments (continued)

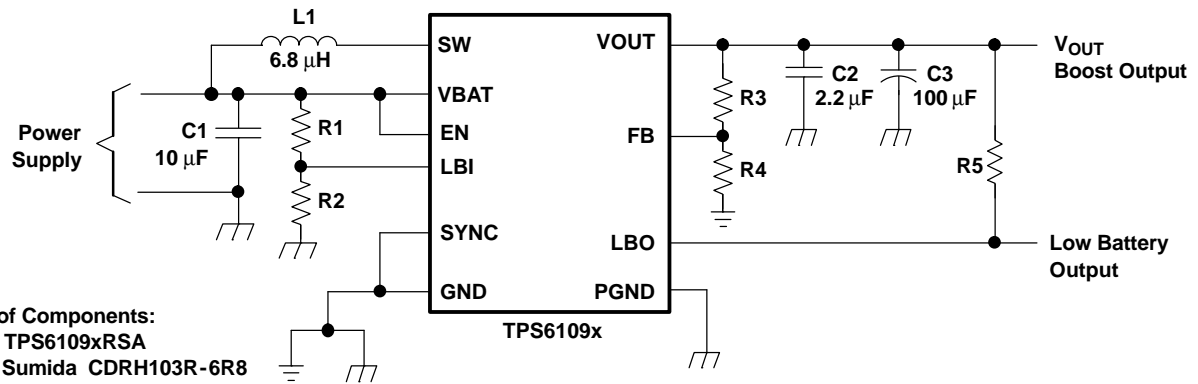
Terminal Functions (continued)

TERMINAL		I/O	DESCRIPTION
NAME	NO.		
GND	13	I/O	Control/logic ground
LBI	9	I	Low battery comparator input (comparator enabled with EN)
LBO	12	O	Low battery comparator output (open drain)
NC	2		Not connected
SYNC	10	I	Enable/disable power save mode (1: VBAT disabled, 0: GND enabled, clock signal for synchronization)
SW	3, 4	I	Boost and rectifying switch input
PGND	5, 6, 7	I/O	Power ground
VBAT	8	I	Supply voltage
VOUT	1, 15, 16	O	DC/DC output
PowerPAD™			Must be soldered to achieve appropriate power dissipation. Should be connected to PGND.

FUNCTIONAL BLOCK DIAGRAM



**PARAMETER MEASUREMENT INFORMATION**



**List of Components:**

- U1 = TPS6109xRSA
- L1 = Sumida CDRH103R-6R8
- C1, C2 = X7R/X5R Ceramic
- C3 = Low ESR Tantalum

TYPICAL CHARACTERISTICS

Table of Graphs

DC/DC Converter		Figure
Maximum output current	vs Input voltage	1, 2
Efficiency	vs Output current (TPS61090) ( $V_O = 2.5\text{ V}$ , $V_I = 1.8\text{ V}$ , $V_{SYNC} = 0\text{ V}$ )	3
	vs Output current (TPS61091) ( $V_O = 3.3\text{ V}$ , $V_I = 1.8\text{ V}$ , $2.4\text{ V}$ , $V_{SYNC} = 0\text{ V}$ )	4
	vs Output current (TPS61092) ( $V_O = 5.0\text{ V}$ , $V_I = 2.4\text{ V}$ , $3.3\text{ V}$ , $V_{SYNC} = 0\text{ V}$ )	5
	vs Input voltage (TPS61091) ( $I_O = 10\text{ mA}$ , $100\text{ mA}$ , $500\text{ mA}$ , $V_{SYNC} = 0\text{ V}$ )	6
	vs Input voltage (TPS61092) ( $I_O = 10\text{ mA}$ , $100\text{ mA}$ , $500\text{ mA}$ , $V_{SYNC} = 0\text{ V}$ )	7
Output voltage	vs Output current (TPS61091) ( $V_I = 2.4\text{ V}$ )	8
	vs Output current (TPS61092) ( $V_I = 3.3\text{ V}$ )	9
No-load supply current into VBAT	vs Input voltage (TPS61092)	10
No-load supply current into VOUT	vs Input voltage (TPS61092)	11
Waveforms	Output voltage in continuous mode (TPS61092)	12
	Output voltage in power save mode (TPS61092)	13
	Load transient response (TPS61092)	14
	Line transient response (TPS61092)	15
	DC/DC converter start-up after enable (TPS61092)	16

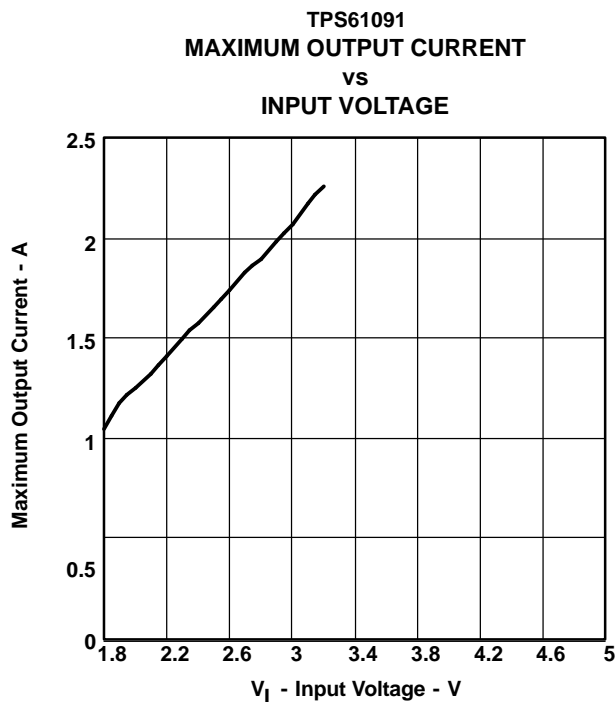


Figure 1.

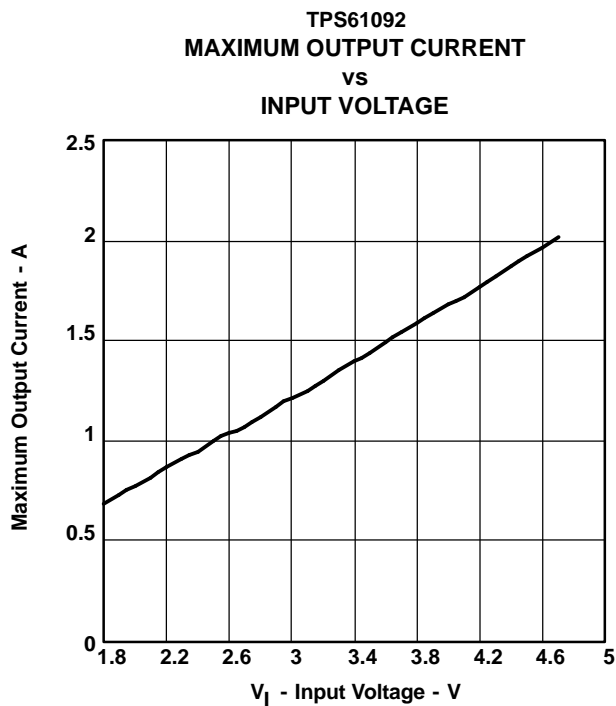


Figure 2.

**TYPICAL CHARACTERISTICS (continued)**

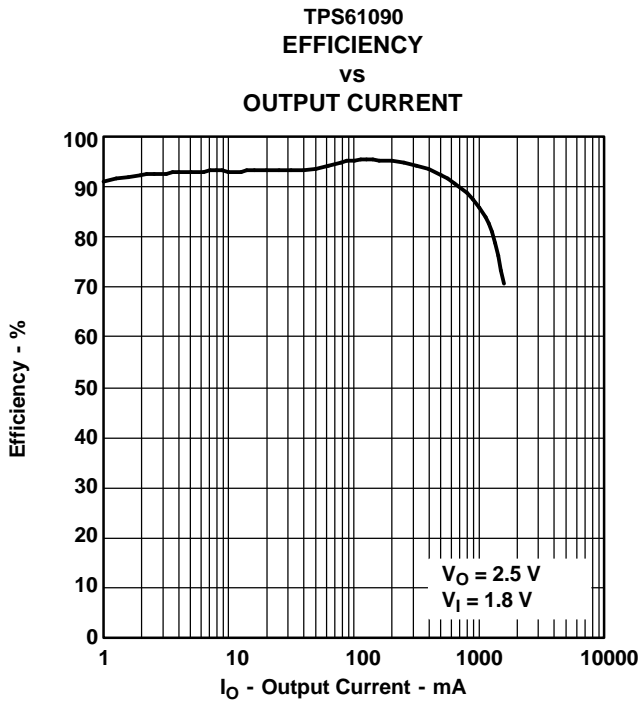


Figure 3.

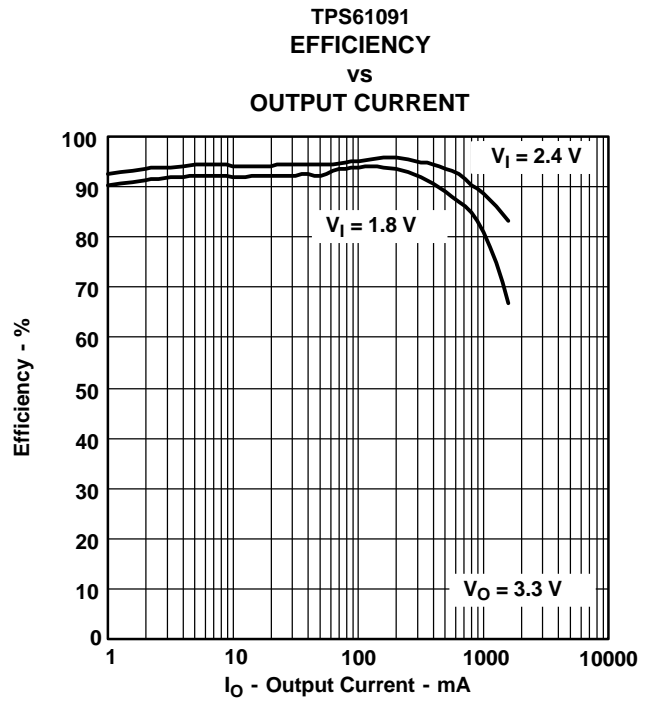


Figure 4.

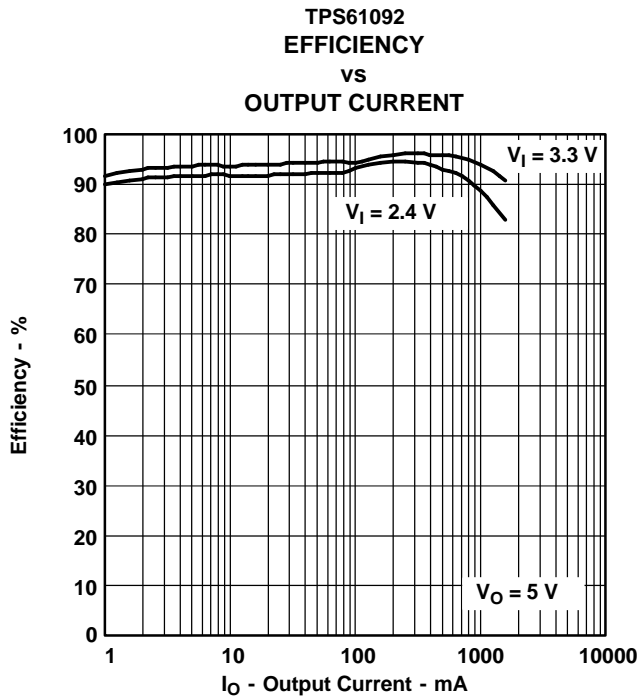


Figure 5.

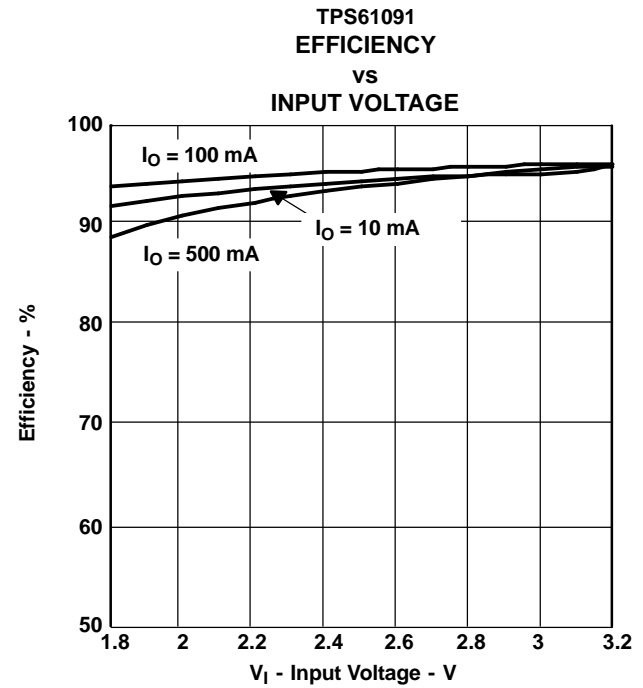
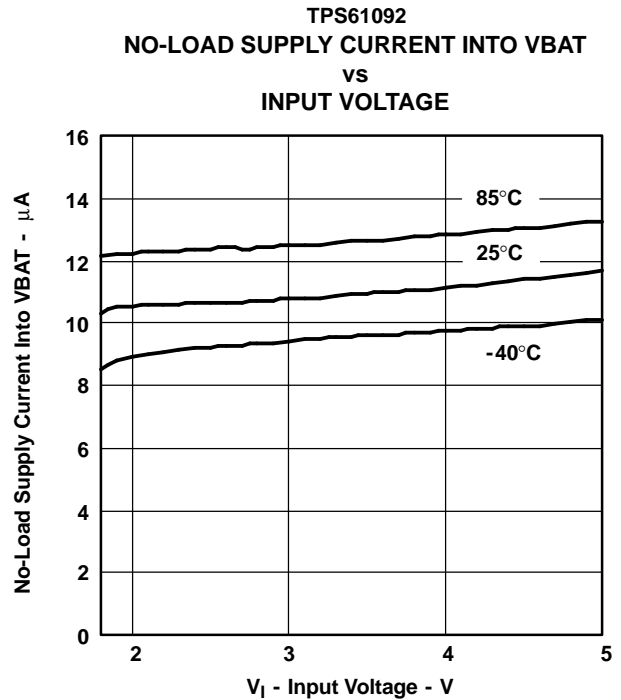
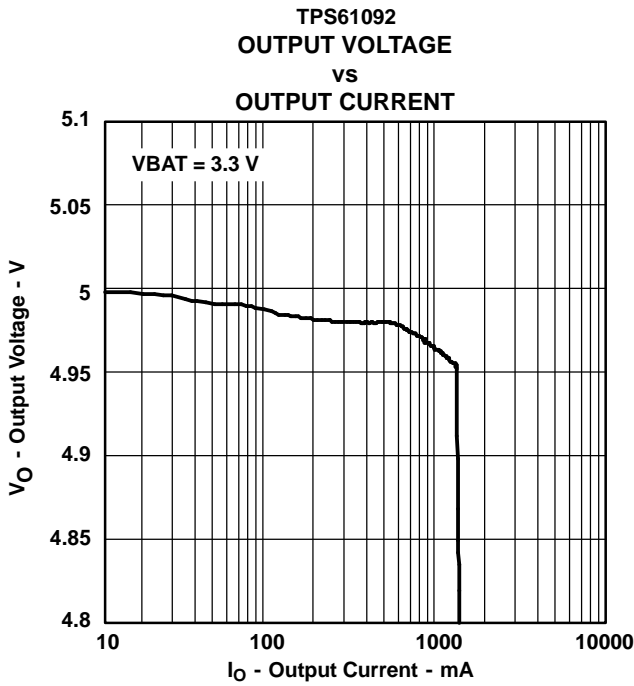
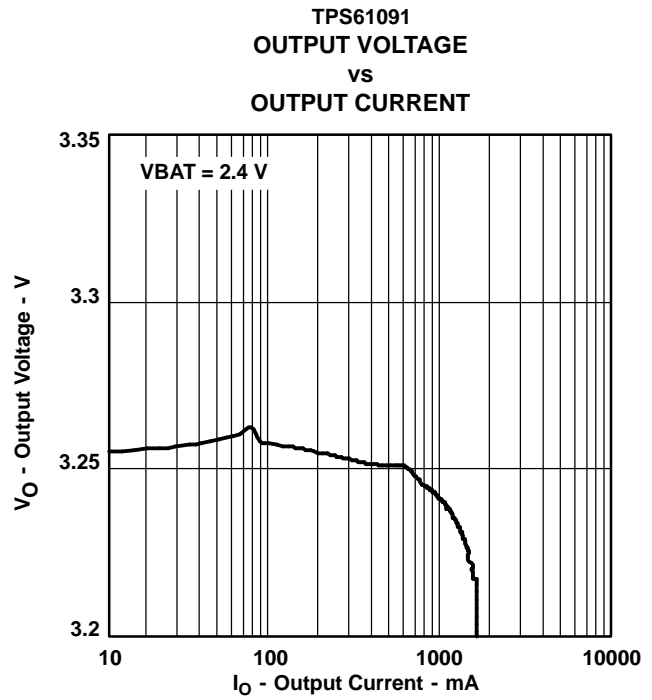
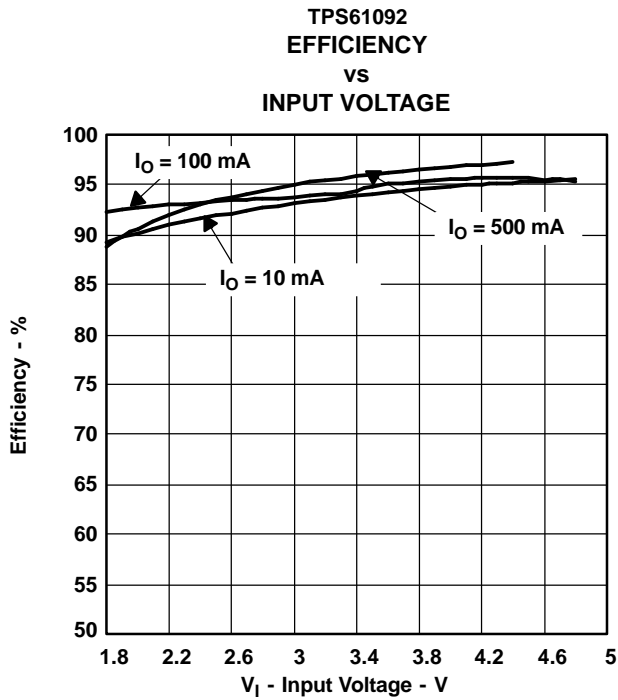


Figure 6.

TYPICAL CHARACTERISTICS (continued)





**TYPICAL CHARACTERISTICS (continued)**

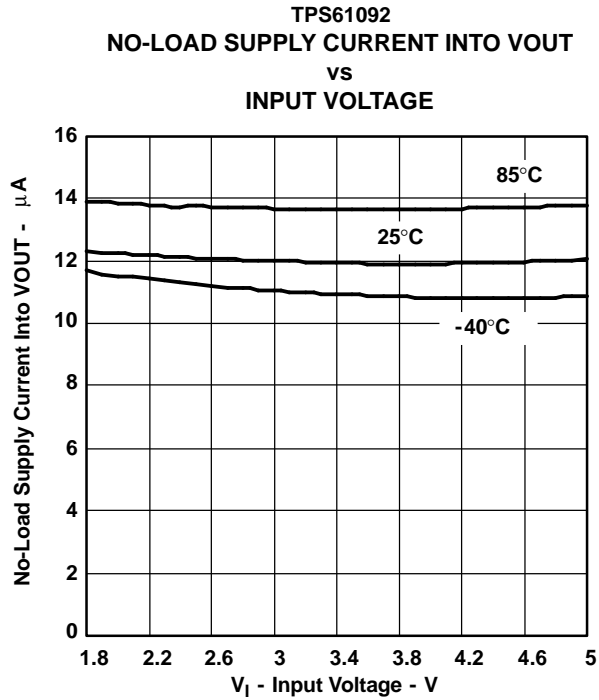


Figure 11.

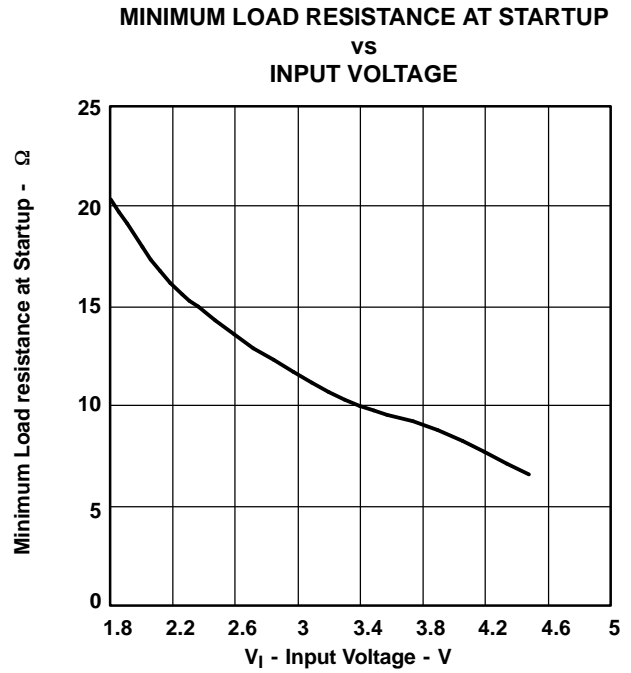


Figure 12.

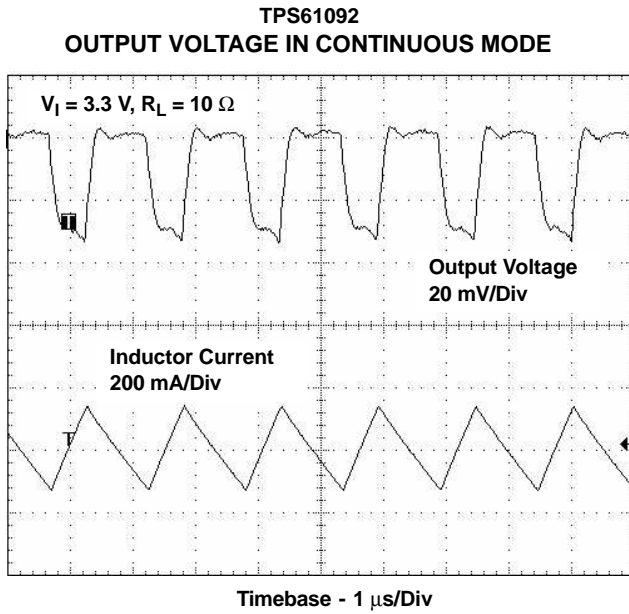


Figure 13.

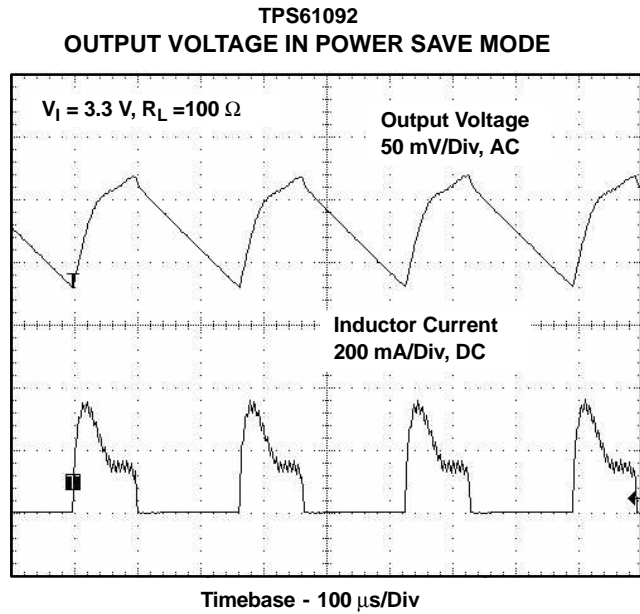
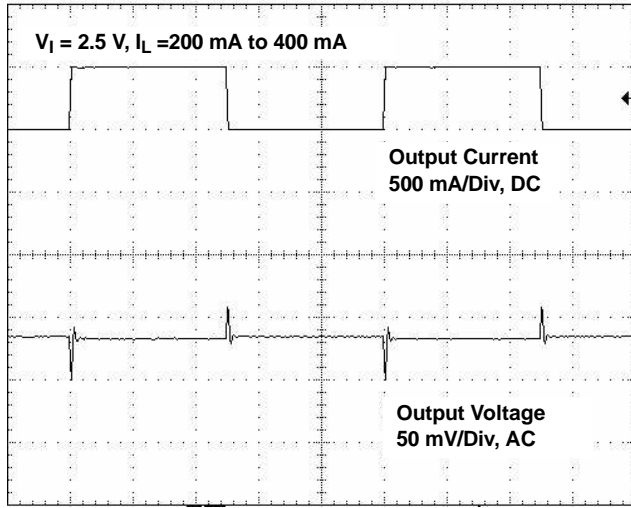


Figure 14.

TYPICAL CHARACTERISTICS (continued)

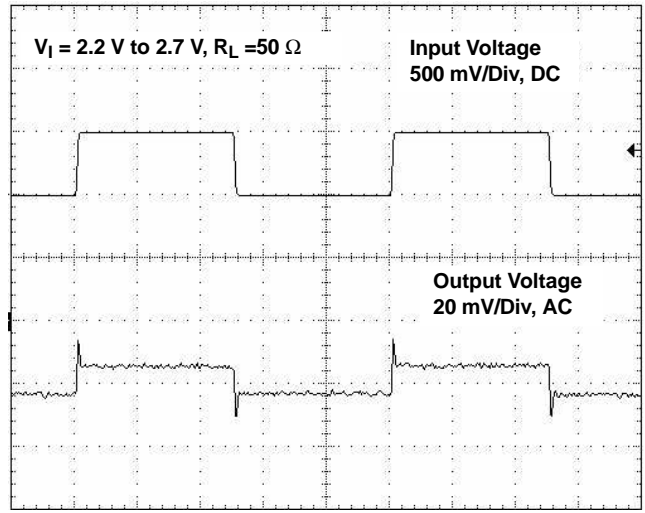
TPS61092  
 LOAD TRANSIENT RESPONSE



Timebase - 2 ms/Div

Figure 15.

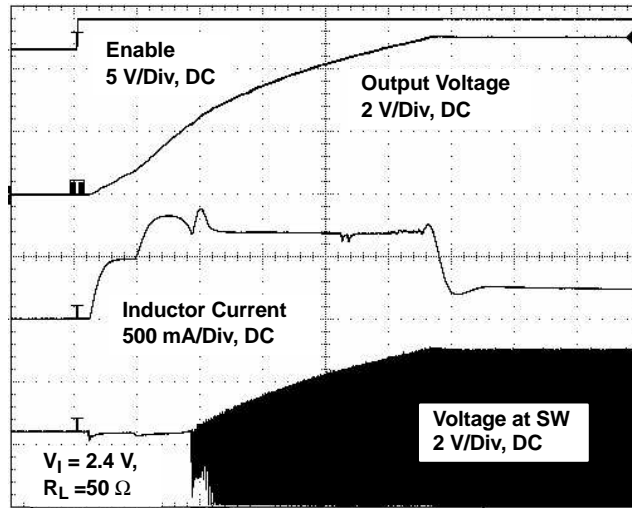
TPS61092  
 LINE TRANSIENT RESPONSE



Timebase - 2 ms/Div

Figure 16.

TPS61092  
 DC/DC CONVERTER START-UP AFTER ENABLE



Timebase - 200 μs/Div

Figure 17.

## APPLICATION INFORMATION

### DESIGN PROCEDURE

The TPS6109x dc/dc converters are intended for systems powered by a dual or triple cell NiCd or NiMH battery with a typical terminal voltage between 1.8 V and 5.5 V. They can also be used in systems powered by one-cell Li-Ion with a typical stack voltage between 2.5 V and 4.2 V. Additionally, two or three primary and secondary alkaline battery cells can be the power source in systems where the TPS6109x is used.

### Programming the Output Voltage

The output voltage of the TPS61090 dc/dc converter section can be adjusted with an external resistor divider. The typical value of the voltage on the FB pin is 500 mV. The maximum allowed value for the output voltage is 5.5 V. The current through the resistive divider should be about 100 times greater than the current into the FB pin. The typical current into the FB pin is 0.01  $\mu$ A, and the voltage across R4 is typically 500 mV. Based on those two values, the recommended value for R4 should be lower than 500 k $\Omega$ , in order to set the divider current at 1  $\mu$ A or higher. Because of internal compensation circuitry the value for this resistor should be in the range of 200 k $\Omega$ . From that, the value of resistor R3, depending on the needed output voltage ( $V_O$ ), can be calculated using Equation 1:

$$R3 = R4 \times \left( \frac{V_O}{V_{FB}} - 1 \right) = 200 \text{ k}\Omega \times \left( \frac{V_O}{500 \text{ mV}} - 1 \right) \quad (1)$$

If as an example, an output voltage of 5.0 V is needed, a 1.8-M $\Omega$  resistor should be chosen for R3. If for any reason the value for R4 is chosen significantly lower than 200 k $\Omega$  additional capacitance in parallel to R3 is recommended. The required capacitance value can be easily calculated using Equation 2

$$C_{\text{par}R3} = 10 \text{ pF} \times \left( \frac{200 \text{ k}\Omega}{R4} - 1 \right) \quad (2)$$

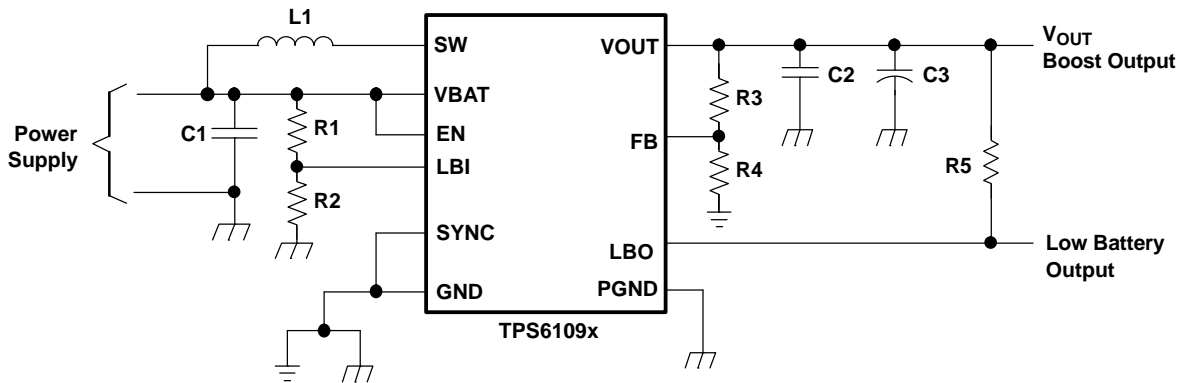


Figure 18. Typical Application Circuit for Adjustable Output Voltage Option

### Programming the LBI/LBO Threshold Voltage

The current through the resistive divider should be about 100 times greater than the current into the LBI pin. The typical current into the LBI pin is 0.01  $\mu$ A, and the voltage across R2 is equal to the LBI voltage threshold that is generated on-chip, which has a value of 500 mV. The recommended value for R2 is therefore in the range of 500 k $\Omega$ . From that, the value of resistor R1, depending on the desired minimum battery voltage  $V_{BAT}$ , can be calculated using Equation 3.

## APPLICATION INFORMATION (continued)

$$R1 = R2 \times \left( \frac{V_{BAT}}{V_{LBI} - \text{threshold}} - 1 \right) = 390 \text{ k}\Omega \times \left( \frac{V_{BAT}}{500 \text{ mV}} - 1 \right) \quad (3)$$

The output of the low battery supervisor is a simple open-drain output that goes active low if the dedicated battery voltage drops below the programmed threshold voltage on LBI. The output requires a pullup resistor with a recommended value of 1 M $\Omega$ . The maximum voltage which is used to pull up the LBO outputs should not exceed the output voltage of the dc/dc converter. If not used, the LBO pin can be left floating or tied to GND.

## Inductor Selection

A boost converter normally requires two main passive components for storing energy during the conversion. A boost inductor and a storage capacitor at the output are required. To select the boost inductor, it is recommended to keep the possible peak inductor current below the current limit threshold of the power switch in the chosen configuration. For example, the current limit threshold of the TPS6109x's switch is 2500 mA at an output voltage of 5 V. The highest peak current through the inductor and the switch depends on the output load, the input ( $V_{BAT}$ ), and the output voltage ( $V_{OUT}$ ). Estimation of the maximum average inductor current can be done using Equation 4:

$$I_L = I_{OUT} \times \frac{V_{OUT}}{V_{BAT} \times 0.8} \quad (4)$$

For example, for an output current of 500 mA at 5 V, at least 1750 mA of average current flows through the inductor at a minimum input voltage of 1.8 V.

The second parameter for choosing the inductor is the desired current ripple in the inductor. Normally, it is advisable to work with a ripple of less than 20% of the average inductor current. A smaller ripple reduces the magnetic hysteresis losses in the inductor, as well as output voltage ripple and EMI. But in the same way, regulation time at load changes rises. In addition, a larger inductor increases the total system costs. With those parameters, it is possible to calculate the value for the inductor by using Equation 5:

$$L = \frac{V_{BAT} \times (V_{OUT} - V_{BAT})}{\Delta I_L \times f \times V_{OUT}} \quad (5)$$

Parameter  $f$  is the switching frequency and  $\Delta I_L$  is the ripple current in the inductor, i.e.,  $20\% \times I_L$ . In this example, the desired inductor has the value of 5.5  $\mu\text{H}$ . With this calculated value and the calculated currents, it is possible to choose a suitable inductor. Care has to be taken that load transients and losses in the circuit can lead to higher currents as estimated in equation 4. Also, the losses in the inductor caused by magnetic hysteresis losses and copper losses are a major parameter for total circuit efficiency.

The following inductor series from different suppliers have been used with the TPS6109x converters:

### List of Inductors

VENDOR	INDUCTOR SERIES
Sumida	CDRH6D28
	CDRH6D38
	CDRH103R
Würth Elektronik	WE-PD type L
	WE-PD type XL
EPCOS	B82464G

## Capacitor Selection

### Input Capacitor

At least a 10- $\mu$ F input capacitor is recommended to improve transient behavior of the regulator and EMI behavior of the total power supply circuit. A ceramic capacitor or a tantalum capacitor with a 100-nF ceramic capacitor in parallel, placed close to the IC, is recommended.

### Output Capacitor DC/DC Converter

The major parameter necessary to define the minimum value of the output capacitor is the maximum allowed output voltage ripple in steady state operation of the converter. This ripple is determined by two parameters of the capacitor, the capacitance and the ESR. It is possible to calculate the minimum capacitance needed for the defined ripple, supposing that the ESR is zero, by using equation Equation 6:

$$C_{\min} = \frac{I_{\text{OUT}} \times (V_{\text{OUT}} - V_{\text{BAT}})}{f \times \Delta V \times V_{\text{OUT}}} \quad (6)$$

Parameter  $f$  is the switching frequency and  $\Delta V$  is the maximum allowed ripple.

With a chosen ripple voltage of 10 mV, a minimum capacitance of 53  $\mu$ F is needed. The total ripple is larger due to the ESR of the output capacitor. This additional component of the ripple can be calculated using Equation 7:

$$\Delta V_{\text{ESR}} = I_{\text{OUT}} \times R_{\text{ESR}} \quad (7)$$

An additional ripple of 40 mV is the result of using a tantalum capacitor with a low ESR of 80 m $\Omega$ . The total ripple is the sum of the ripple caused by the capacitance and the ripple caused by the ESR of the capacitor. In this example, the total ripple is 50 mV. Additional ripple is caused by load transients. This means that the output capacitance needs to be larger than calculated above to meet the total ripple requirements. The output capacitor has to completely supply the load during the charging phase of the inductor. A reasonable value of the output capacitance depends on the speed of the load transients and the load current during the load change. With the calculated minimum value of 53  $\mu$ F and load transient considerations, a reasonable output capacitance value is in a 100  $\mu$ F range. For economical reasons this usually is a tantalum capacitor. Because of this the control loop has been optimized for using output capacitors with an ESR of above 30 m $\Omega$ .

### Small Signal Stability

When using output capacitors with lower ESR, like ceramics, it is recommended to use the adjustable voltage version. The missing ESR can be easily compensated there in the feedback divider. Typically a capacitor in the range of 10 pF in parallel to R3 helps to obtain small signal stability with lowest ESR output capacitors. For more detailed analysis the small signal transfer function of the error amplifier and regulator, which is given is Equation 8, can be used.

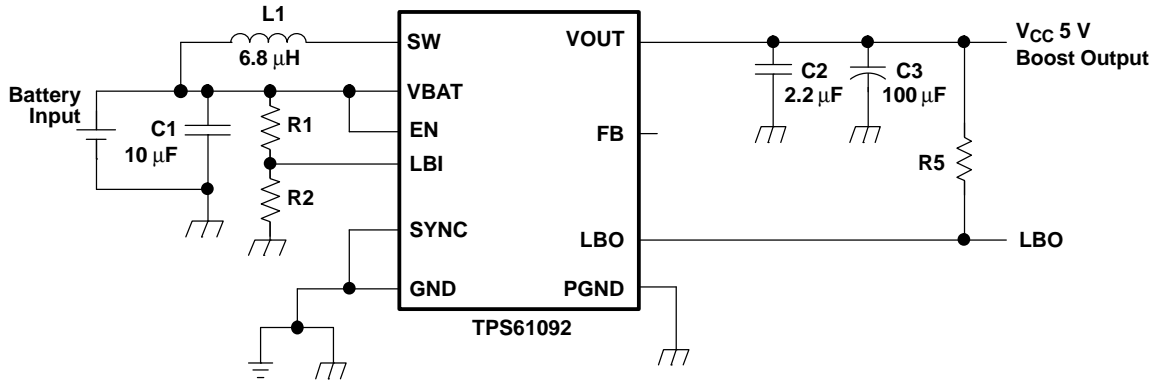
$$A_{\text{REG}} = \frac{d}{V_{\text{FB}}} \quad A_{\text{REG}} = \frac{d5(R3 + R4)}{R4 \times (1 + i \times \omega \times 2.3 \mu\text{s})} \quad (8)$$

## LAYOUT CONSIDERATIONS

As for all switching power supplies, the layout is an important step in the design, especially at high peak currents and high switching frequencies. If the layout is not carefully done, the regulator could show stability problems as well as EMI problems. Therefore, use wide and short traces for the main current path and for the power ground tracks. The input capacitor, output capacitor, and the inductor should be placed as close as possible to the IC. Use a common ground node for power ground and a different one for control ground to minimize the effects of ground noise. Connect these ground nodes at any place close to one of the ground pins of the IC.

The feedback divider should be placed as close as possible to the control ground pin of the IC. To lay out the control ground, it is recommended to use short traces as well, separated from the power ground traces. This avoids ground shift problems, which can occur due to superimposition of power ground current and control ground current.

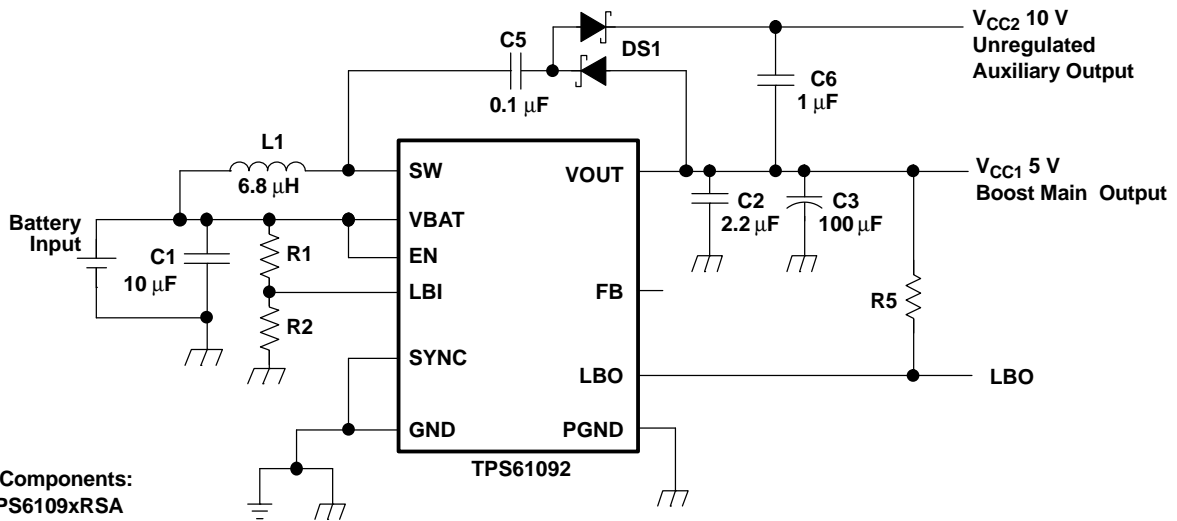
APPLICATION INFORMATION



List of Components:

- U1 = TPS6109xRSA
- L1 = Sumida CDRH103R-6R8
- C1, C2 = X7R,X5R Ceramic
- C3 = Low ESR Tantalum

Figure 19. Power Supply Solution for Maximum Output Power

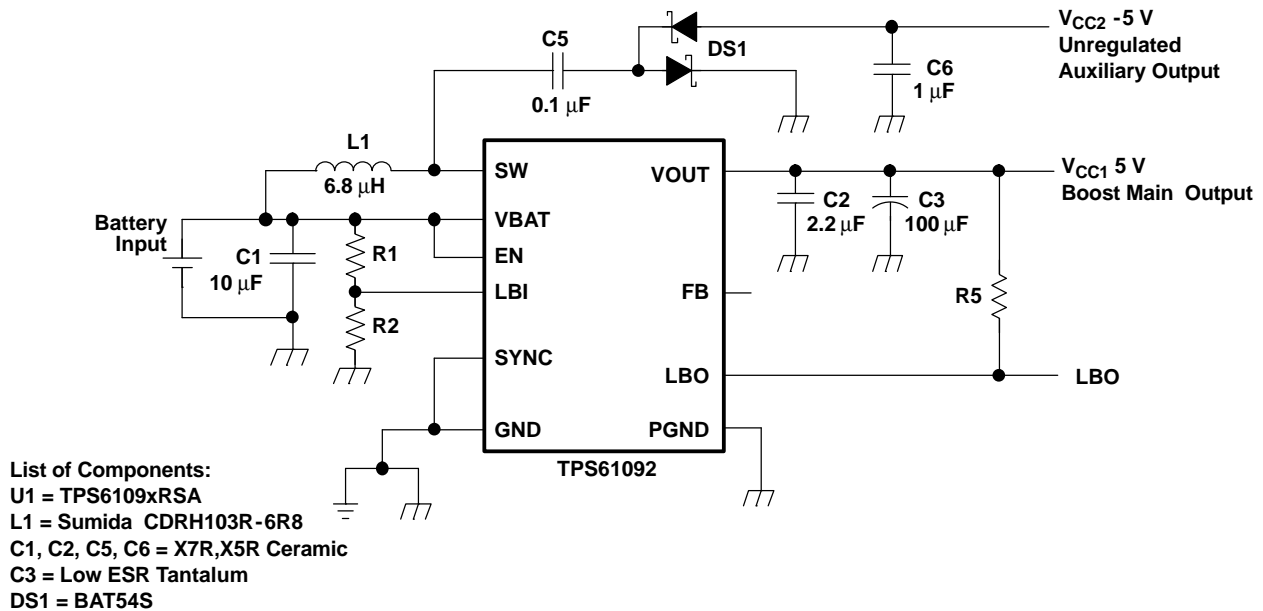


List of Components:

- U1 = TPS6109xRSA
- L1 = Sumida CDRH103R-6R8
- C1, C2, C5, C6, = X7R,X5R Ceramic
- C3 = Low ESR Tantalum
- DS1 = BAT54S

Figure 20. Power Supply Solution With Auxiliary Positive Output Voltage

## Application Information (continued)



**Figure 21. Power Supply Solution With Auxiliary Negative Output Voltage**

## DETAILED DESCRIPTION

### Synchronous Rectifier

The device integrates an N-channel and a P-channel MOSFET transistor to realize a synchronous rectifier. Because the commonly used discrete Schottky rectifier is replaced with a low RDS(ON) PMOS switch, the power conversion efficiency reaches 96%. To avoid ground shift due to the high currents in the NMOS switch, two separate ground pins are used. The reference for all control functions is the GND pin. The source of the NMOS switch is connected to PGND. Both grounds must be connected on the PCB at only one point close to the GND pin. A special circuit is applied to disconnect the load from the input during shutdown of the converter. In conventional synchronous rectifier circuits, the backgate diode of the high-side PMOS is forward biased in shutdown and allows current flowing from the battery to the output. This device however uses a special circuit which takes the cathode of the backgate diode of the high-side PMOS and disconnects it from the source when the regulator is not enabled (EN = low).

The benefit of this feature for the system design engineer is that the battery is not depleted during shutdown of the converter. No additional components have to be added to the design to make sure that the battery is disconnected from the output of the converter.

### Controller Circuit

The controller circuit of the device is based on a fixed frequency multiple feedforward controller topology. Input voltage, output voltage, and voltage drop on the NMOS switch are monitored and forwarded to the regulator. So changes in the operating conditions of the converter directly affect the duty cycle and must not take the indirect and slow way through the control loop and the error amplifier. The control loop, determined by the error amplifier, only has to handle small signal errors. The input for it is the feedback voltage on the FB pin or, at fixed output voltage versions, the voltage on the internal resistor divider. It is compared with the internal reference voltage to generate an accurate and stable output voltage.

The peak current of the NMOS switch is also sensed to limit the maximum current flowing through the switch and the inductor. The typical peak current limit is set to 2200 mA.

An internal temperature sensor prevents the device from getting overheated in case of excessive power dissipation.

## **Detailed Description (continued)**

### **Device Enable**

The device is put into operation when EN is set high. It is put into a shutdown mode when EN is set to GND. In shutdown mode, the regulator stops switching, all internal control circuitry including the low-battery comparator is switched off, and the load is isolated from the input (as described in the Synchronous Rectifier Section). This also means that the output voltage can drop below the input voltage during shutdown. During start-up of the converter, the duty cycle and the peak current are limited in order to avoid high peak currents drawn from the battery.

### **Undervoltage Lockout**

An undervoltage lockout function prevents device start-up if the supply voltage on VBAT is lower than typically 1.6 V. When in operation and the battery is being discharged, the device automatically enters the shutdown mode if the voltage on VBAT drops below approximately 1.6 V. This undervoltage lockout function is implemented in order to prevent the malfunctioning of the converter.

### **Softstart**

When the device enables the internal startup cycle starts with the first step, the precharge phase. During precharge, the rectifying switch is turned on until the output capacitor is charged to a value close to the input voltage. The rectifying switch current is limited in that phase. This also limits the output current under short-circuit conditions at the output. After charging the output capacitor to the input voltage the device starts switching. Until the output voltage is reached, the boost switch current limit is set to 40% of its nominal value to avoid high peak currents at the battery during startup. When the output voltage is reached, the regulator takes control and the switch current limit is set back to 100%.

### **Power Save Mode and Synchronization**

The SYNC pin can be used to select different operation modes. To enable power save, SYNC must be set low. Power save mode is used to improve efficiency at light load. In power save mode the converter only operates when the output voltage trips below a set threshold voltage. It ramps up the output voltage with one or several pulses and goes again into power save mode once the output voltage exceeds the set threshold voltage. This power save mode can be disabled by setting the SYNC to VBAT.

Applying an external clock with a duty cycle between 30% and 70% at the SYNC pin forces the converter to operate at the applied clock frequency. The external frequency has to be in the range of about  $\pm 20\%$  of the nominal internal frequency. Detailed values are shown in the electrical characteristic section of the data sheet.

### **Low Battery Detector Circuit—LBI/LBO**

The low-battery detector circuit is typically used to supervise the battery voltage and to generate an error flag when the battery voltage drops below a user-set threshold voltage. The function is active only when the device is enabled. When the device is disabled, the LBO pin is high-impedance. The switching threshold is 500 mV at LBI. During normal operation, LBO stays at high impedance when the voltage, applied at LBI, is above the threshold. It is active low when the voltage at LBI goes below 500 mV.

The battery voltage, at which the detection circuit switches, can be programmed with a resistive divider connected to the LBI pin. The resistive divider scales down the battery voltage to a voltage level of 500 mV, which is then compared to the LBI threshold voltage. The LBI pin has a built-in hysteresis of 10 mV. See the application section for more details about the programming of the LBI threshold. If the low-battery detection circuit is not used, the LBI pin should be connected to GND (or to VBAT) and the LBO pin can be left unconnected. Do not let the LBI pin float.



## Low-EMI Switch

The device integrates a circuit that removes the ringing that typically appears on the SW node when the converter enters discontinuous current mode. In this case, the current through the inductor ramps to zero and the rectifying PMOS switch is turned off to prevent a reverse current flowing from the output capacitors back to the battery. Due to the remaining energy that is stored in parasitic components of the semiconductor and the inductor, a ringing on the SW pin is induced. The integrated antiringing switch clamps this voltage to VBAT and therefore dampens ringing.

## THERMAL INFORMATION

Implementation of integrated circuits in low-profile and fine-pitch surface-mount packages typically requires special attention to power dissipation. Many system-dependent issues such as thermal coupling, airflow, added heat sinks and convection surfaces, and the presence of other heat-generating components affect the power-dissipation limits of a given component.

Three basic approaches for enhancing thermal performance are listed below.

- Improving the power dissipation capability of the PCB design
- Improving the thermal coupling of the component to the PCB
- Introducing airflow in the system

The maximum junction temperature ( $T_J$ ) of the TPS6109x devices is 150°C. The thermal resistance of the 16-pin QFN PowerPAD package (RSA) is  $R_{\theta JA} = 38.1 \text{ }^\circ\text{C/W}$ , if the PowerPAD is soldered and the board layout is optimized. Specified regulator operation is assured to a maximum ambient temperature  $T_A$  of 85°C. Therefore, the maximum power dissipation is about 1700 mW. More power can be dissipated if the maximum ambient temperature of the application is lower.

$$P_{D(\text{MAX})} = \frac{T_{J(\text{MAX})} - T_A}{R_{\theta JA}} = \frac{150^\circ\text{C} - 85^\circ\text{C}}{38.1 \text{ k/W}} = 1700 \text{ mW}$$

If designing for a lower junction temperature of 125°C, which is recommended, maximum heat dissipation is lower. Using the above equation (8) results in 1050 mW power dissipation.

**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
TPS61090RSAR	ACTIVE	QFN	RSA	16	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
TPS61090RSARG4	ACTIVE	QFN	RSA	16	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
TPS61091RSAR	ACTIVE	QFN	RSA	16	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
TPS61091RSARG4	ACTIVE	QFN	RSA	16	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
TPS61092RSAR	ACTIVE	QFN	RSA	16	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
TPS61092RSARG4	ACTIVE	QFN	RSA	16	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

**Important Information and Disclaimer:**The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

**TAPE AND REEL INFORMATION**



**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPS61090RSAR	QFN	RSA	16	3000	330.0	12.4	4.3	4.3	1.5	8.0	12.0	Q2
TPS61091RSAR	QFN	RSA	16	3000	330.0	12.4	4.3	4.3	1.5	8.0	12.0	Q2
TPS61092RSAR	QFN	RSA	16	3000	330.0	12.4	4.3	4.3	1.5	8.0	12.0	Q2

**TAPE AND REEL BOX DIMENSIONS**

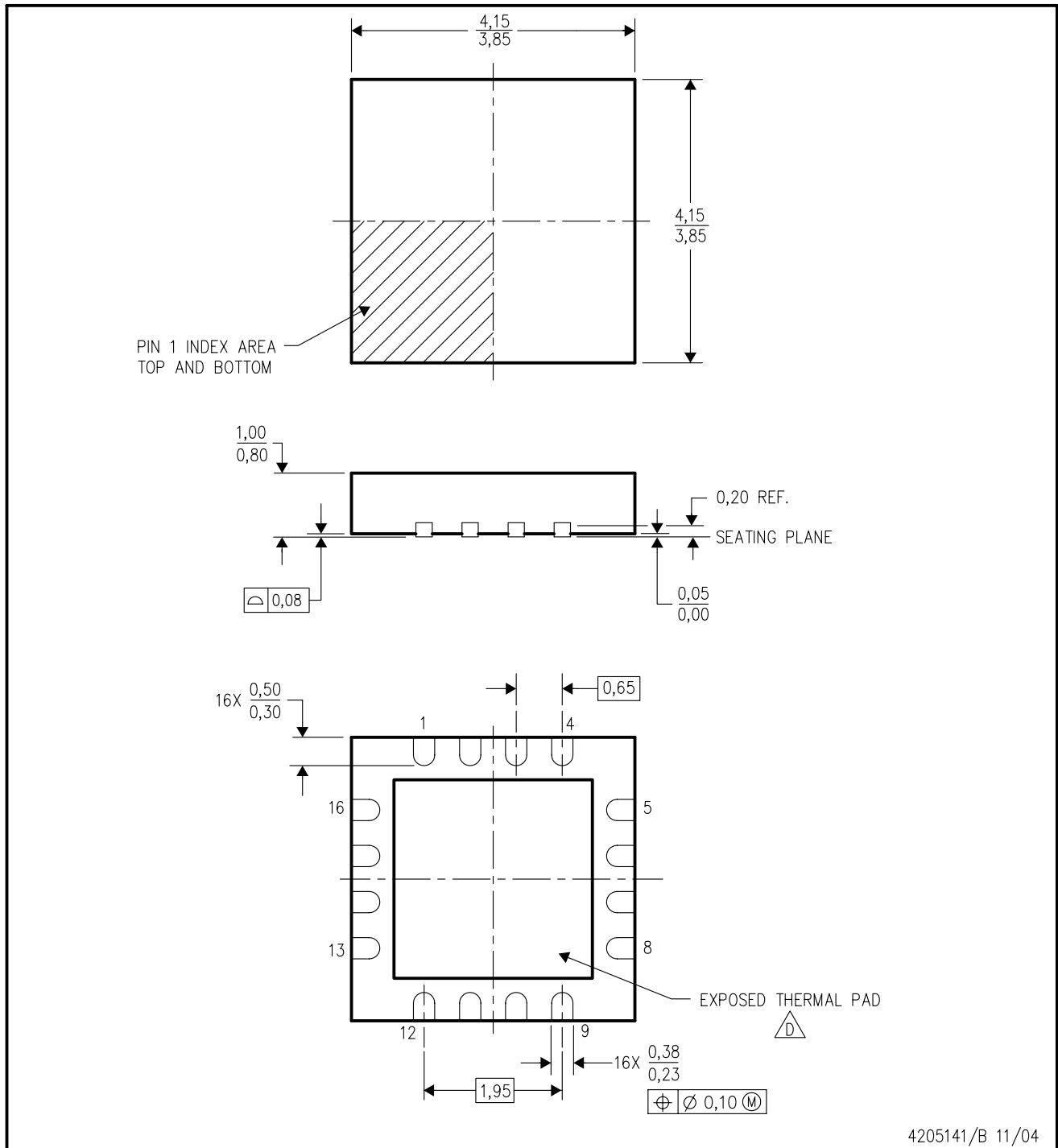


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPS61090RSAR	QFN	RSA	16	3000	340.5	333.0	20.6
TPS61091RSAR	QFN	RSA	16	3000	340.5	333.0	20.6
TPS61092RSAR	QFN	RSA	16	3000	340.5	333.0	20.6

RSA (S-PQFP-N16)

PLASTIC QUAD FLATPACK



4205141/B 11/04

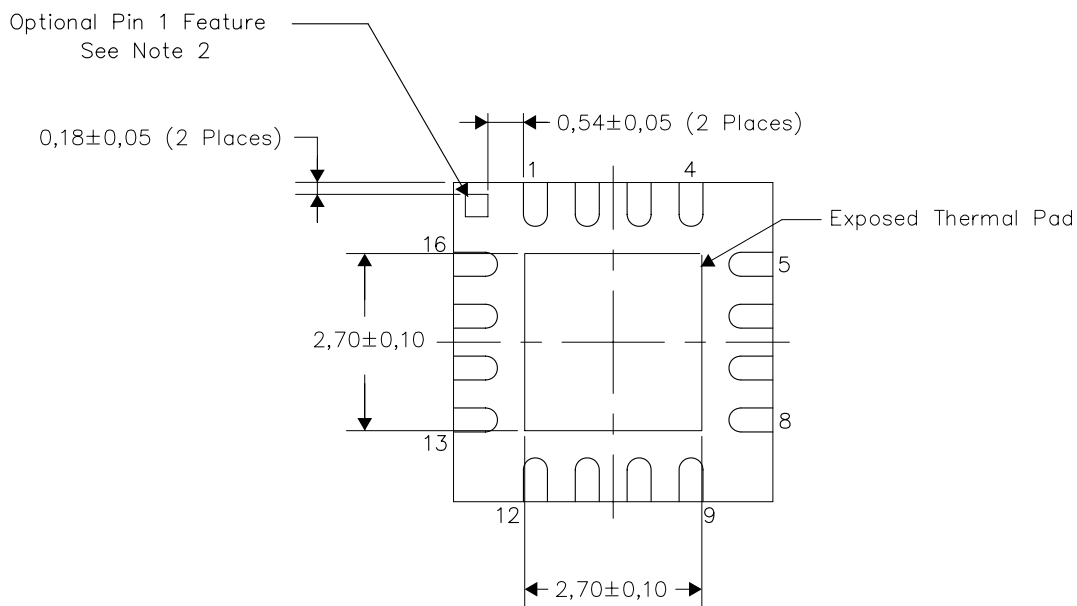
- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - C. Quad Flatpack, No-leads (QFN) package configuration.
  - △ The package thermal pad must be soldered to the board for thermal and mechanical performance. See the Product Data Sheet for details regarding the exposed thermal pad dimensions.
  - E. Falls within JEDEC MO-220.

**THERMAL INFORMATION**

This package incorporates an exposed thermal pad that is designed to be attached directly to an external heatsink. The thermal pad must be soldered directly to the printed circuit board (PCB). After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For information on the Quad Flatpack No-Lead (QFN) package and its advantages, refer to Application Report, QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271. This document is available at [www.ti.com](http://www.ti.com).

The exposed thermal pad dimensions for this package are shown in the following illustration.

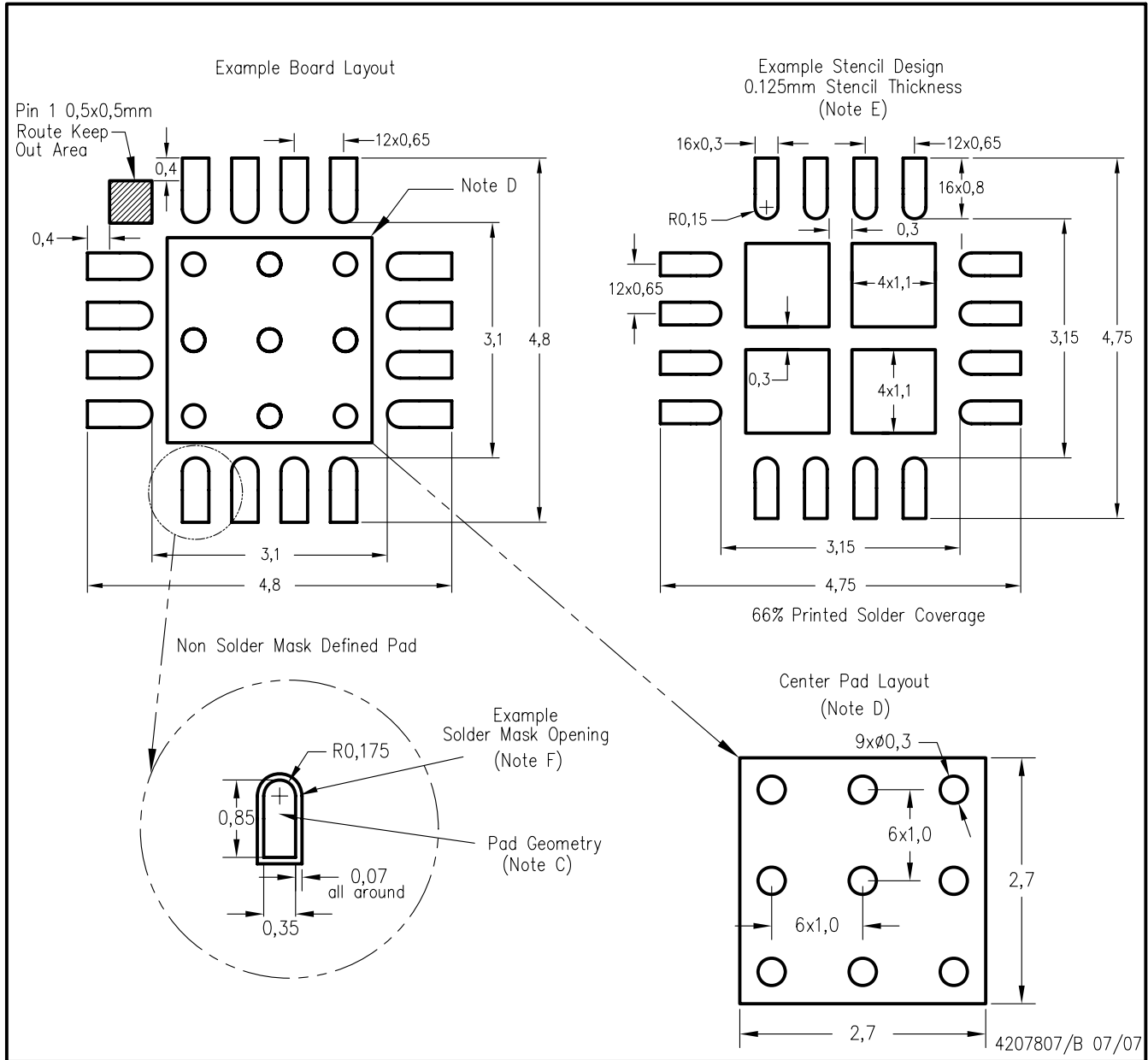


Bottom View  
Exposed Thermal Pad Dimensions

**NOTES:**

- 1) All linear dimensions are in millimeters
- 2) The Pin 1 Identification mark is an optional feature that may be present on some devices. In addition, this Pin 1 feature if present is electrically connected to the center thermal pad and therefore should be considered when routing the board layout.

RSA (S-PQFP-N16)



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Publication IPC-7351 is recommended for alternate designs.
  - D. This package is designed to be soldered to a thermal pad on the board. Refer to Application Note, QFN Packages, Texas Instruments Literature No. SCBA017, SLUA271, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at [www.ti.com](http://www.ti.com) <<http://www.ti.com>>.
  - E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
  - F. Customers should contact their board fabrication site for solder mask tolerances.

## IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

### Products

Amplifiers	<a href="http://amplifier.ti.com">amplifier.ti.com</a>
Data Converters	<a href="http://dataconverter.ti.com">dataconverter.ti.com</a>
DSP	<a href="http://dsp.ti.com">dsp.ti.com</a>
Clocks and Timers	<a href="http://www.ti.com/clocks">www.ti.com/clocks</a>
Interface	<a href="http://interface.ti.com">interface.ti.com</a>
Logic	<a href="http://logic.ti.com">logic.ti.com</a>
Power Mgmt	<a href="http://power.ti.com">power.ti.com</a>
Microcontrollers	<a href="http://microcontroller.ti.com">microcontroller.ti.com</a>
RFID	<a href="http://www.ti-rfid.com">www.ti-rfid.com</a>
RF/IF and ZigBee® Solutions	<a href="http://www.ti.com/lprf">www.ti.com/lprf</a>

### Applications

Audio	<a href="http://www.ti.com/audio">www.ti.com/audio</a>
Automotive	<a href="http://www.ti.com/automotive">www.ti.com/automotive</a>
Broadband	<a href="http://www.ti.com/broadband">www.ti.com/broadband</a>
Digital Control	<a href="http://www.ti.com/digitalcontrol">www.ti.com/digitalcontrol</a>
Medical	<a href="http://www.ti.com/medical">www.ti.com/medical</a>
Military	<a href="http://www.ti.com/military">www.ti.com/military</a>
Optical Networking	<a href="http://www.ti.com/opticalnetwork">www.ti.com/opticalnetwork</a>
Security	<a href="http://www.ti.com/security">www.ti.com/security</a>
Telephony	<a href="http://www.ti.com/telephony">www.ti.com/telephony</a>
Video & Imaging	<a href="http://www.ti.com/video">www.ti.com/video</a>
Wireless	<a href="http://www.ti.com/wireless">www.ti.com/wireless</a>

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265  
Copyright © 2008, Texas Instruments Incorporated